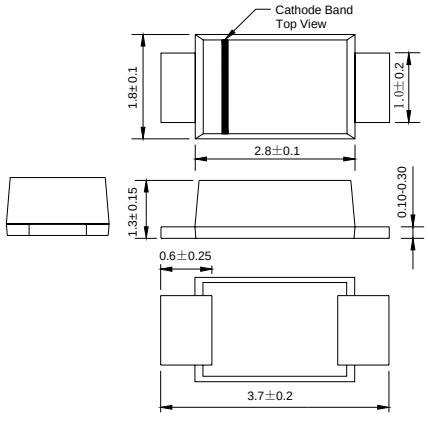
SOD-123FL



Dimensions in millimeters

FEATURES

- Glass passivated device
- Ideal for surface mouted applications
- Low reverse leakage
- Metallurgically bonded construction
- High temperature soldering guaranteed:
  250℃/10 seconds,0.375"(9.5mm) lead length,
  5 lbs. (2.3kg) tension

MECHANICAL DATA

Case: JEDEC SOD-123FL molded plastic body over passivated chip
Terminals: Plated axial leads, solderable per MIL-STD-750, Method 2026
Polarity: Color band denotes cathode end
Mounting Position: Any
Weight:0.006 ounce, 0.02 grams

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25℃ ambient temperature unless otherwise specified.
Single phase half-wave 60Hz,resistive or inductive load,for capacitive load current derate by 20%.

	SYMBOLS	FFM157-M F57	UNITS
Maximum repetitive peak reverse voltage	V_{RRM}	1000	VOLTS
Maximum RMS voltage	V_{RMS}	700	VOLTS
Maximum DC blocking voltage	V_{DC}	1000	VOLTS
Maximum average forward rectified current at T_A=65℃ (NOTE 1)	$I_{(AV)}$	1.5	Amp
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method) T_L=25℃	I_{FSM}	50.0	Amps
Maximum instantaneous forward voltage at 1.5A	V_F	1.3	Volts
Maximum DC reverse current T_A=25℃ at rated DC blocking voltage T_A=125℃	I_R	5.0 50.0	μA
Maximum reverse recovery time (NOTE 2)	trr	500	ns
Typical junction capacitance (NOTE 3)	C_J	4	pF
Typical thermal resistance (NOTE 4)	$R_{\theta JA}$	180	K/W
Operating junction and storage temperature range	T_J,T_{STG}	-55 to +150	℃

Note: 1.Averaged over any 20ms period.
2.Measured with IF=0.5A, IR=1A, Irr=0.25A.
3.Measured at 1MHz and applied reverse voltage of 4.0V D.C.
4.Thermal resistance junction to ambient, 6.0 mm2 coppeer pads to each terminal.

FIG.1 –TYPICAL FORWARD CHARACTERISTIC

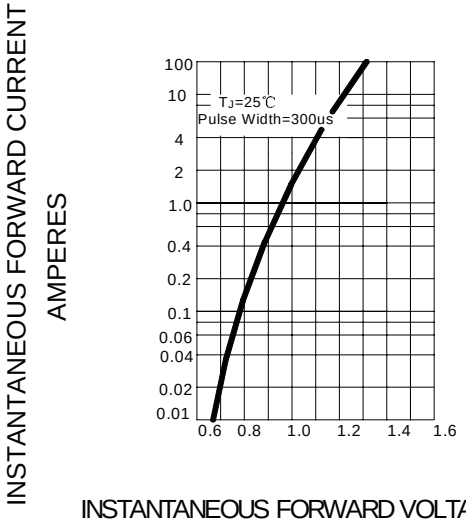


FIG.2 – TYPICAL JUNCTION CAPACITANCE

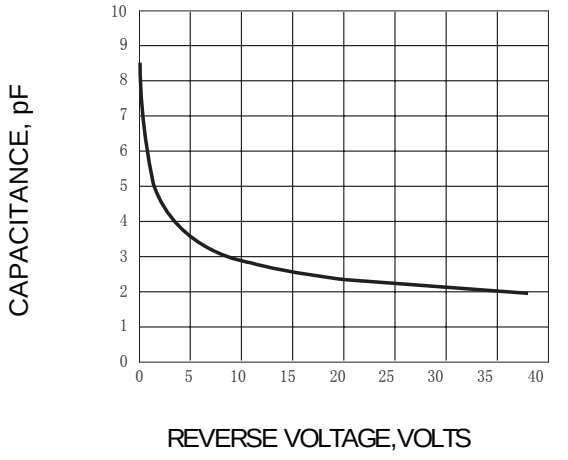


FIG.3 – TYPICAL INSTANTANEOUS REVERSE CHARACTERISTICS

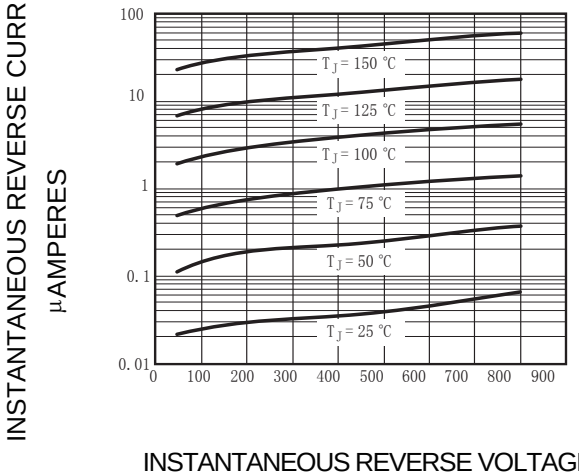


FIG.4 – FORWARD DERATING CURVE